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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/083,160	02/27/2002	Masanori Minamio	740819-753	7465
22204	7590	03/25/2003		
NIXON PEABODY, LLP 8180 GREENSBORO DRIVE SUITE 800 MCLEAN, VA 22102			EXAMINER THAI, LUAN C	
			ART UNIT 2827	PAPER NUMBER

DATE MAILED: 03/25/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	10/083,160	MINAMIO ET AL.
	Examiner	Art Unit
	Luan Thai	2827

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 21 January 2003.

2a) This action is **FINAL**. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-10 is/are pending in the application.
4a) Of the above claim(s) 6-10 is/are withdrawn from consideration.
5) Claim(s) _____ is/are allowed.
6) Claim(s) 1,2,4 and 5 is/are rejected.
7) Claim(s) 3 is/are objected to.
8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 27 February 2002 is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

11) The proposed drawing correction filed on _____ is: a) approved b) disapproved by the Examiner.
If approved, corrected drawings are required in reply to this Office action.

12) The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some * c) None of:

1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).

a) The translation of the foreign language provisional application has been received.

15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413) Paper No(s). _____ .
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 5) Notice of Informal Patent Application (PTO-152)
3) Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____ 6) Other: _____

DETAILED ACTION

Election/Restrictions

1. Applicant's election of Group I, claims 1-5 in Paper No. 4 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)).

Priority

2. Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d).

Oath/Declaration

3. The declaration filed 02/27/02 is acceptable.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

5. Claims 1 and 4-5 are rejected under 35 U.S.C. 102(b) as being anticipated by Yamaguchi et al (5,977,615).

The figures and reference numbers referred to in this office action are used merely to indicate an example of a specific teaching and are not to be taken as limiting.

Regarding claims 1 and 4-5, Yamaguchi et al (see specifically figure 7 attached, and figures 10, 11a-11b and 13-14) disclose a resin-encapsulated semiconductor device comprising: a die pad 20 (see also die pad 60 in figures 19, 20 and 23); a semiconductor chip 30 mounted on the die pad; a first lead 24a including a first land 27a on a lower surface thereof and a first bonding pad on the first lead's upper surface from which the thin metal wire 31 is bonded for making electrical connection to a portion of the chip 30 (see figure 10); a second lead 24b including a second land 27b on a lower surface thereof and a second bonding pad on the second lead's upper surface from which the thin metal wire 31 is bonded for making electrical connection to a portion of the chip 30 (see figure 10); a third lead 23 including a third land 26 on a lower surface thereof and a third bonding pad on the third lead's upper surface from which the thin metal wire 31 is bonded for making electrical connection to a portion of the chip 30 (see figure 10); an encapsulation resin 32 for encapsulating the semiconductor chip 30, the leads 24a-24b-23, the thin metal wires 31 and the die pad 20, wherein the first lead 24a and the third lead 23 are separated from each other, with one end of the first lead 24a being exposed on a side surface of the encapsulation resin 32 and both ends of the third lead 23 being in the encapsulation resin (see figures 11a-11b). Yamaguchi et al further disclose the first, second and third lands (27a-27b-26) being exposed on a lower surface of the encapsulation resin while being arranged in three rows as viewed in a plan view (see figures 7, 11a-11b and figure 13 attached), and wherein the second lead and a lead structure

including the first and third leads are arranged alternately along a periphery of an opening of a frame body (see figure 7).

Claim Rejections - 35 USC § 103

6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

7. Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaguchi et al (5,977,615) in view of Champagne (6,075,282).

The figures and reference numbers referred to in this office action are used merely to indicate an example of a specific teaching and are not to be taken as limiting.

Regarding claim 2, the semiconductor device of Yamaguchi et al discloses all the limitations of the claimed invention as detailed above except for at least the second lead including a neck portion having a smaller width than other portions as viewed in a plan view.

Champagne while related to a similar resin-encapsulated semiconductor device teaches (see specifically figures 1-4) each of leads 5 including a neck portion 20 having a smaller width than other portions as viewed in a plan view, in order to allow solid encapsulation of the resin and help to minimize the risk of delaminating and to keep the leads correctly positioned with respect to each other (Col. 5, lines 55+). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Yamaguchi et al's device by

forming the second lead including a neck portion having a smaller width than other portions as viewed in a plan view, as taught by Champagne, in order to allow solid encapsulation of the resin and help to minimize the risk of delaminating and to keep the leads correctly positioned with respect to each other.

Allowable Subject Matter

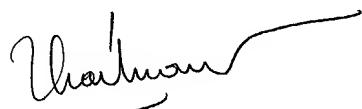
8. Claim 3 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
9. The following is a statement of reasons for the indication of allowable subject matter:

The prior art taken either singly or in combination fails to anticipate or fairly suggest: each lead including a region around the bonding pad thereof that has a smaller thickness than that of a portion of the lead corresponding to the bonding pad, with a stepped portion being provided between the bonding pad and the region around the bonding pad, as recited in claim 3; especially when these limitations are considered within the specific combination claimed.

10. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Luan Thai whose telephone number is (703) 308-1211. The examiner can normally be reached on 7:00 AM - 4:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David L. Talbott can be reached on (703) 305-9883. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.



Luan Thai
March 22, 2003